

Thermal Dispersion Terminals (Heat Sink)

Surface Mount Thermal Dispersion Terminals to reduce temperature in PCB or the mounted components

Application

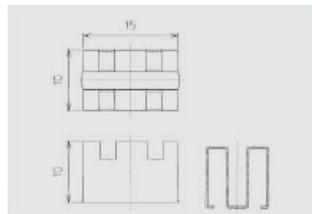
- To transfer heat to the air by mounting around the components emitting heat.

Feature

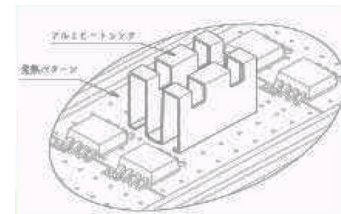
- This is heat dispersion component to be able to solder using excellent heat dispersion plated aluminum.
- Surface area is larger than general heat sink and lighter weight can be achieved to keep heat dispersion effectively.
- Due to press manufacturing, free design is possible in effective use of space in accordance with PCB and circuit design.
- This product can be mounted in the same process as general SMD components.



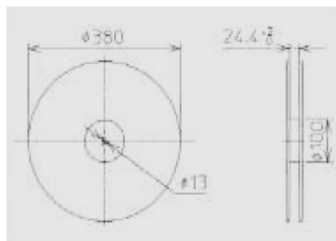
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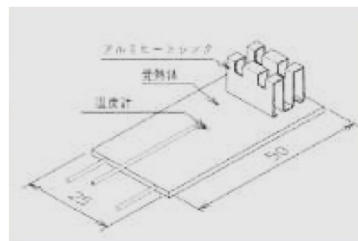
Dimensions



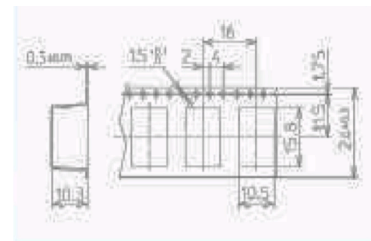
Application Example



Reel Size



Measurement Example



Tape Package

Materials: Solderable Aluminum

Package: Emboss Taping (400 pcs in Reel)

Reference data: Heat Resistance 17.6 [$^{\circ}\text{C}/\text{W}$] (at 3.5W)

This is not guaranteed value due to in house test data based on natural convection environment and effect will be changed depends on application.

Custom design is available. Please consult sales division.

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